

MSM7627 Chipset Training

Introductions and Chipset Overview

80-VM151-21 Rev. A

Qualcomm Confidential and Proprietary

Restricted Distribution. Not to be distributed to anyone who is not an employee of either Qualcomm or a subsidiary of Qualcomm without the express approval of Qualcomm's Configuration Management.

Not to be used, copied, reproduced in whole or in part, nor its contents revealed in any manner to others without the express written permission of Qualcomm.

QUALCOMM is a registered trademark of QUALCOMM Incorporated in the United States and may be registered in other countries. Other product and brand names may be trademarks or registered trademarks of their respective owners. CDMA2000 is a registered certification mark of the Telecommunications Industry Association, used under license. ARM is a registered trademark of ARM Limited. QDSP is a registered trademark of QUALCOMM Incorporated in the United States and other countries.

This technical data may be subject to U.S. and international export, re-export, or transfer ("export") laws. Diversion contrary to U.S. and international law is strictly prohibited.

QUALCOMM Incorporated
5775 Morehouse Drive
San Diego, CA 92121-1714
U.S.A.

Copyright © 2009 QUALCOMM Incorporated
All rights reserved.

Terms and Conditions of Usage

This document may contain information regarding parts and products whose manufacture, use, sale, offer for sale, or importation into the United States is subject to restrictions under one or more U.S. injunctions against QUALCOMM Incorporated. This document is not to be construed as an offer to sell such parts or products for use or importation into the U.S. This document is intended solely to provide technical information regarding technical recommendations and/or requirements regarding uses and configurations of those parts or products inside and outside the United States that are permitted by such injunctions. Recipient's download and/or use of the information in this document constitutes agreement with these terms.

Revision History

Revision	Date	Description
A	April 2009	Initial release



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

3

Agenda

- MSM7627™ chipset definition
- Feature comparison and key messages
- Chipset overview
 - RF
 - PMIC
 - Bluetooth®
 - WLAN
- Chipset documents



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

4

Key Messages

■ Chipset definition

- 65 nm baseband: MSM7627 (12 × 12 NSP)
- RF Choices
 - ◆ Multimode: RTR6500™ and RTR6285™ IC
 - ◆ 1x only: RTR6500 IC
- PMIC: PM7540™
- Bluetooth: BTS4025™
- WLAN: Atheros AR6002™

■ Chipset hardware schedule

- Engineering samples (ES) in January 2009
- Commercial samples (CS) in May 2009



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

5

Key Messages (cont.)

■ Improvements compared to MSM7625™ and MSM7600™/MSM7500A™

- Bus/processor speed enhancements
 - ◆ 200 MHz AXI and AHB bus
 - ◆ 400 MHz ARM9™
 - ◆ 600 MHz ARM11™
- 256 kB ARM11 L2 cache
- ARM11 floating point
- IMEM 256 kB (128 kB dedicated to graphics)
- 512 kB ADSP L2 cache
- 3D Graphics – Adreno 200
 - ◆ 27 M triangles/sec
 - ◆ Open GL ES 2.0, Open VG1.1, SVG Tiny 1.2
- Boot from SD
- WVGA MDDI/LCDC support, video encoding and decoding



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

6

Key Messages (cont.)

- Software compatibility with MSM7625
 - Same modem, RF, PMIC, companion chips (BT, WiFi, etc.)
- Close pin-compatibility with MSM7625
 - Package size of 12 × 12 NSP



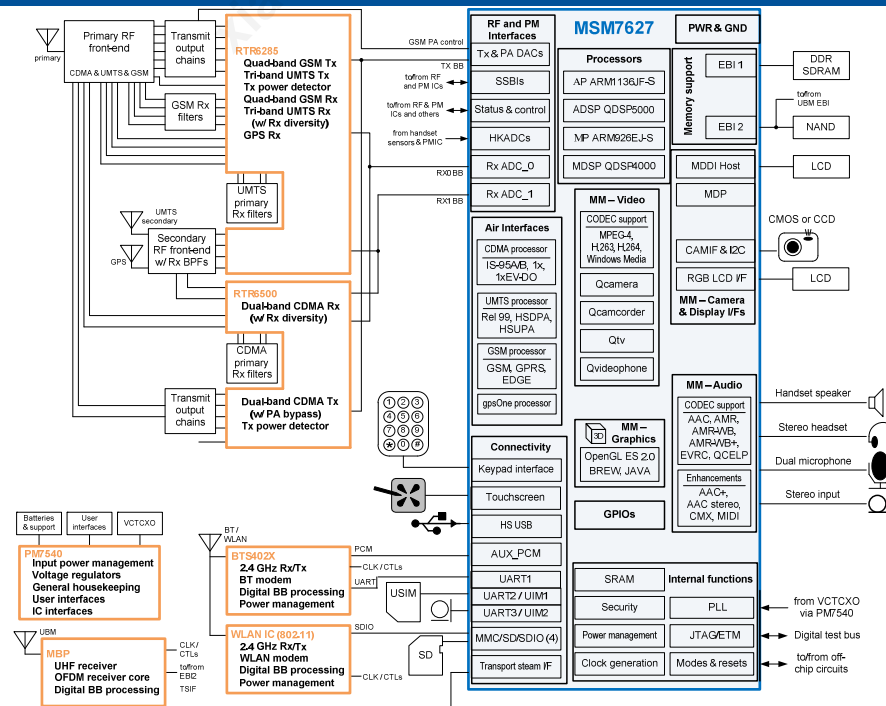
80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

7

MSM7627 System Block Diagram



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

8

MSM7627 Chipset Configurations

■ Hardware configurations

PMIC	BT/WLAN	Baseband modem	RF configuration
PM7540	BTS4025 + AR6002	MSM7627	RTR6500 (1x-only)
			RTR6500 + RTR6285 (multimode)
			RTR6500 + MXU6219 (multimode)

- **Bold** = default configuration in reference schematics

■ Supported software

	BREW	Windows Mobile	Android	Symbian
Software support	√	√	√	√



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

9

MSM7627 Chipset Comparison

Features	MSM7600/MSM7500A	MSM7625	MSM7627
Process technology	65 nm CMOS (15 × 15 × 1.4 mm) 543 CSP	65 nm CMOS (11 × 11 × 1.05 mm) 456 NSP	65 nm CMOS (12 × 12 × 1.05 mm) 560 NSP
Processor	ARM1136-J™ 528 MHz/528 MHz* (apps) ARM926EJ-S™ 320 MHz/256 MHz* (modem) QDSP5000® 320 MHz/256 MHz* (apps) QDSP4000 122.88 MHz (modem)	ARM1136-J 528 MHz/528 MHz* (apps) ARM926EJ-S 320 MHz/256 MHz* (modem) QDSP5000 256 MHz (apps) QDSP4000 122.88 MHz (modem)	ARM1136JF-S 600 MHz (apps) ARM926EJ-S 400 MHz (modem) QDSP5000 320 MHz (apps) QDSP4000 122.88 MHz (modem)
Modem	IS-2000 CDMA 1X, IS-856 1xEV-DO Rev. A, WCDMA, GSM, GPRS, EDGE, DTM, HSDPA 7.2 Mbps, HSUPA 5.76 Mbps, Concurrency 7.2 Mbps DL + 2 Mbps UL	IS-2000 CDMA 1X, IS-856 1xEV-DO Rev. A, WCDMA, GSM, GPRS, EDGE, DTM, HSDPA 7.2 Mbps, HSUPA 5.76 Mbps, Concurrency 7.2 Mbps DL + 2 Mbps UL	IS-2000 CDMA 1X, IS-856 1xEV-DO Rev. A, WCDMA, GSM, GPRS, EDGE, DTM, HSDPA 7.2 Mbps, HSUPA 5.76 Mbps, Concurrency 7.2 Mbps DL + 2 Mbps UL
Rx enhancements	Equalizer, Rx diversity, SAIC	Equalizer, Rx diversity, SAIC	Equalizer, Rx diversity, SAIC
LCD support	16-bit/18-bit/24-bit (EBI2) 16-bit/18-bit/24-bit (MDDI)	16-bit/18-bit/24-bit (EBI2) 16-bit/18-bit/24-bit (MDDI) 16-bit/18-bit/24-bit LCD (RGB) controller	16-bit/18-bit/24-bit (EBI2) 16-bit/18-bit/24-bit (MDDI) 16-bit/18-bit/24-bit LCD (RGB) controller
MDDI support	Yes (two hosts and one client)	Yes (one host)	Yes (one host)
Broadcast interface	TSIF (DVB-H, ISDB-T, S-DMB)	TSIF (DVB-H, ISDB-T, S-DMB)	TSIF (DVB-H, ISDB-T, S-DMB)
Memory	Stacked: 256 Mbit 166 MHz DDR-SDRAM External: 32-bit 166 MHz DDR-SDRAM 8-bit/16-bit NAND flash 16-bit DeMUX OneNAND™	Stacked: N/A External: 32-bit 166 MHz DDR-SDRAM 8-bit/16-bit NAND flash 16-bit MUX OneNAND	Stacked: N/A External: 32-bit 200 MHz DDR-SDRAM 8-bit/16-bit NAND flash 16-bit MUX OneNAND
UART	Four (two HS and two standard)	Four (two HS and two standard)	Four (two HS and two standard)
SDIO	Four	Four	Four
Qcamera™ (viewfinder frame rate)	8 megapixel support MDDI – 30 fps WVGA	5 megapixel support MDDI – 30 fps VGA LCDC – 30 fps WQVGA	8 megapixel support MDDI – 30 fps WVGA LCDC – 30 fps WVGA
OS	ARM11: L4, Windows Mobile®, Linux® ARM9™: L4	ARM11: L4, WinMob, Linux ARM9: L4	ARM11: L4, WinMob, Linux ARM9: L4

Green text indicates different features than the MSM7625 device.
Red text indicates different features than the MSM7600/MSM7500A device.



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

10

MSM7627 Chipset Comparison (cont.)

Features	MSM7600/MSM7500A	MSM7625	MSM7627
Qcamcorder™ (offline video encoding)	30 fps WVGA	24 fps QVGA	30 fps WVGA
Qtv™ (video decode)	30 fps WVGA streaming 30 fps VGA offline	15 fps WQVGA streaming 30 fps WQVGA offline	15 fps VGA streaming 30 fps WVGA offline
Qvideophone™ (video telephony)	15 fps QCIF	15 fps QCIF	15 fps QCIF
Audio/video decoders	MP3, AAC, AAC+, EAAC+, ADPCM, MPEG4, H263, H264, WMA v9, AMR-NB	MP3, AAC, AAC+, EAAC+, ADPCM, MPEG4, H263, H264, WMA v9, AMR-NB	MP3, AAC, AAC+, EAAC+, ADPCM, MPEG4, H263, H264, WMA v9, AMR-NB
2D/3D graphics acceleration	Hardware acceleration - 2 M - 4 M triangles/sec - 133 megapixels/sec	Not available	Adreno™ 200 WVGA 27 M triangles/sec 133 megapixels/sec fill rate Open GL®-ES 2.0/OpenVG 1.1/ SVG Tiny 1.2
Simultaneous polyphonic tones	128 polyphony Wavetable MIDI	128 polyphony Wavetable MIDI	128 polyphony Wavetable MIDI
Bluetooth®	BT 2.1 + EDR (BTS4025™ device)	BT 2.1 + EDR (BTS4025 device)	BT 2.1 + EDR (BTS4025 device)
USB	High-speed USB OTG (external PHY)	High-speed USB OTG (built-in PHY)	High-speed USB OTG (built-in PHY)
GPS	Standalone and assisted	Standalone and assisted	Standalone and assisted
USIM	Supports dual-voltage USIM via PMIC	Built-in support for dual-voltage USIM	Built-in support for dual-voltage USIM
UICC	One UICC	One UICC	One UICC
Digital rights management (DRM)	OMA DRM v2.0	OMA DRM v2.0	OMA DRM v2.0

Green text indicates different features than the MSM7625 device.
Red text indicates different features than the MSM7600/MSM7500A device.



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

11

RF Overview

RTR6285 and RTR6500



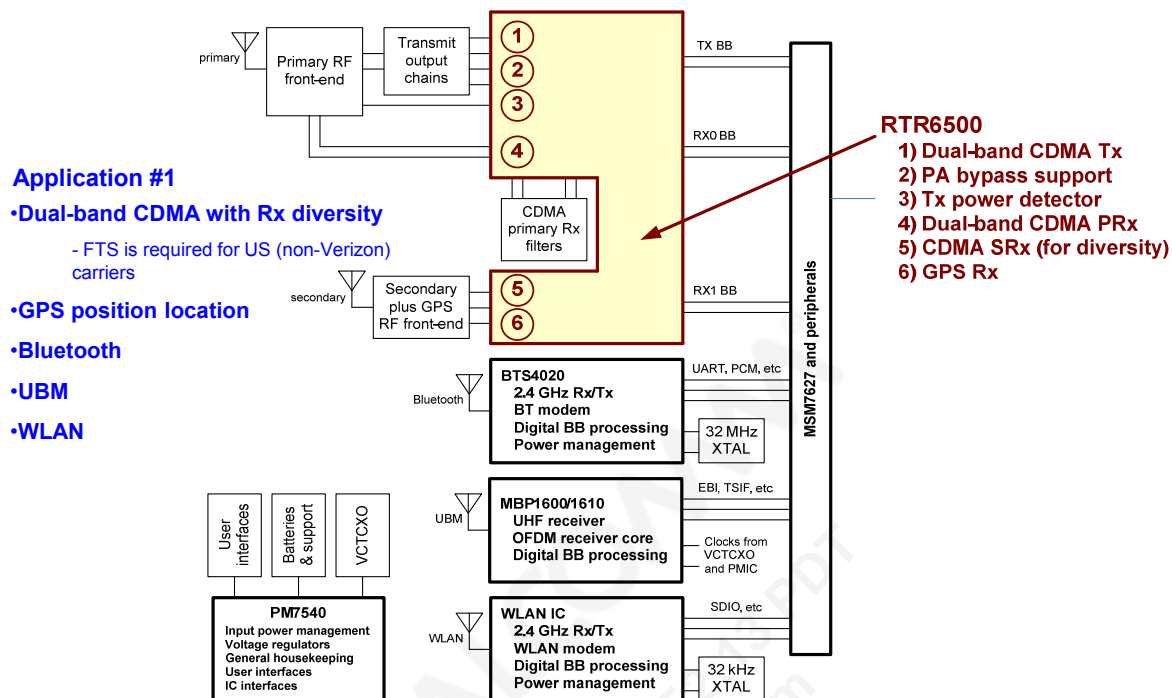
80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

12

RF Architectures – 1x only



QUALCOMM®
CDMA Technologies

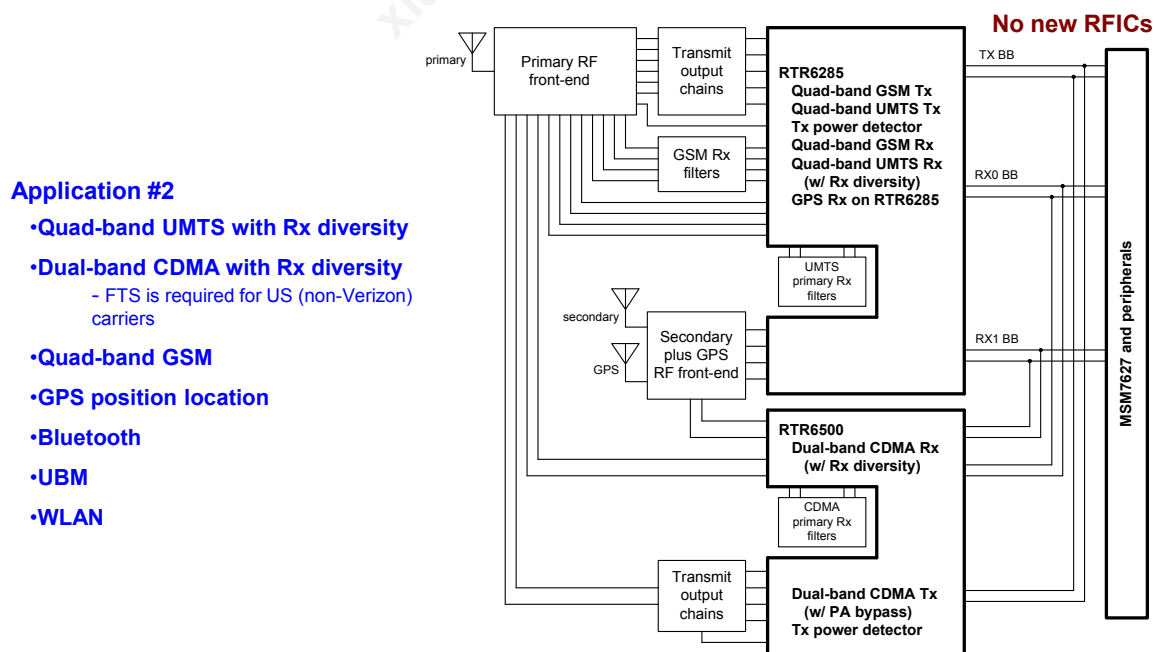
80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

13

RF Architectures – Multimode



Plus Bluetooth, UBM, WLAN, and power management from other examples



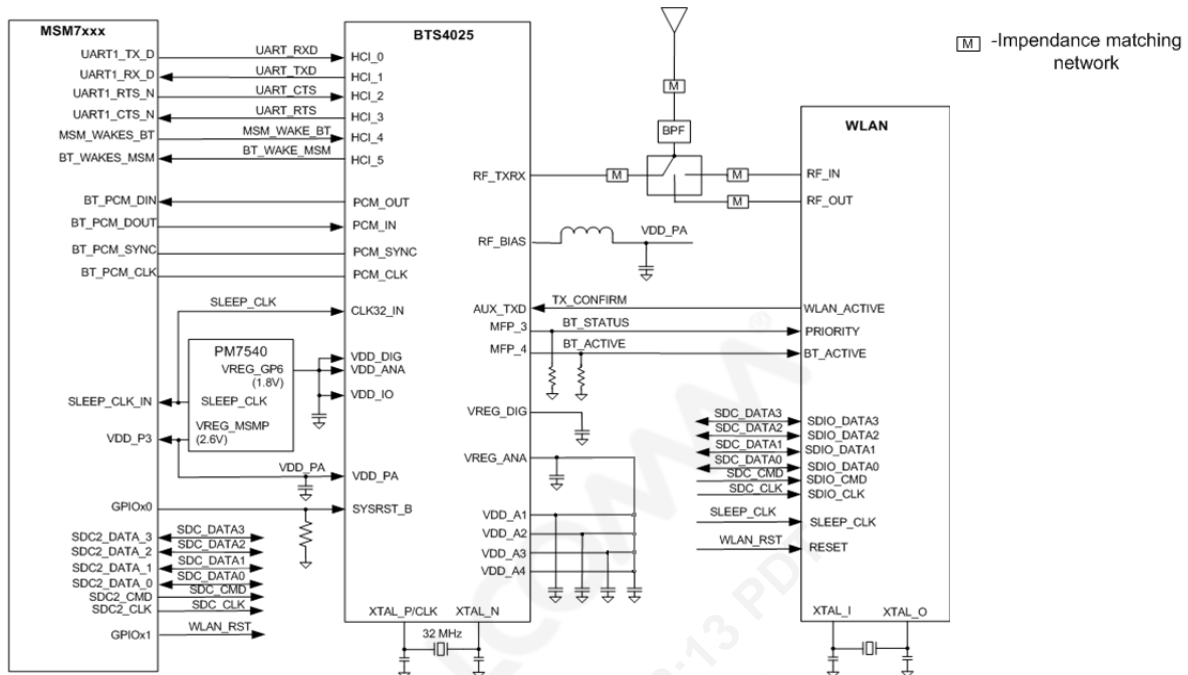
80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

14

BTS4025™ and WLAN Interface



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

17

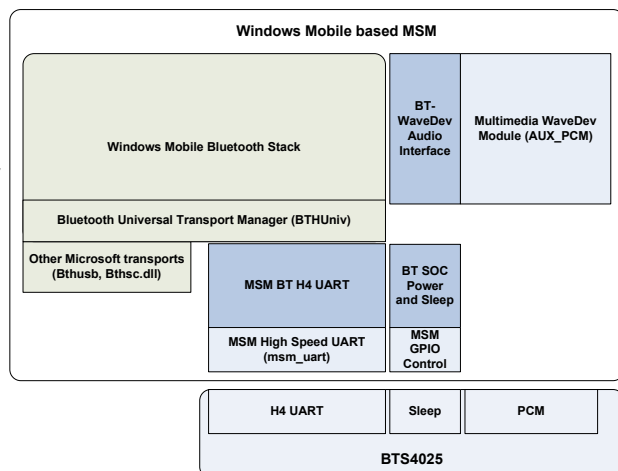
Bluetooth Software Plans

■ Deliverables

- Deliver a working and tested solution with the Windows Mobile upper-layer stack and profiles
 - Bluetooth 2.1 + EDR via BTS4025
 - High-speed UART interface and driver integration
 - PCM interface and audio control
 - Bluetooth power management and control

● BTS4025 features

- Low active and standby current consumption
- Great RF performance



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

18

Power Management Overview

PM7540



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

19

Power Management IC Features

- Complete power management, housekeeping, and user interface functions for wireless devices – CDMA and non-CDMA handsets, modems, PC cards, PDAs, etc.
- This list of features is organized according to the five major functional blocks

Feature description

1) Input Power Management

Valid external supply attachment and removal detection
Supports external charger supplies and USB supplies as input power sources
Supports lithium-ion main batteries
Main battery charging (trickle, constant current, constant voltage, pulsed)
Supports coin cell back-up battery (including charging)
Battery voltage detectors with programmable thresholds
Under-voltage lockout function turns off IC at severely low VDD condition
VDD collapse protection
Charger current regulation and real-time monitoring for over-current protection
Charger transistor protection by power limit control
Control drivers for two external pass transistors and one battery MOSFET (optional)
Voltage, current, and power control loops
Automated recovery from Sudden Momentary Power Loss



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

20

Power Management IC Features (Cont.)

2) Output Voltage Regulation

- One boost (step-up) switched-mode power supply (SMPS)
- Four buck (step-down) switched-mode power supplies
- 18 low dropout regulator circuits with programmable output voltages
- One MIC bias regulator circuit
- Regulators can be individually enabled / disabled to save power
- Supports dynamic voltage scaling (DVS) for MSMC1, MSMC2, and PA outputs
- Low power mode available on most regulators
- All regulated outputs are derived from common reference - close tracking

3) General Housekeeping

- Analog multiplexer selects from 5 internal and up to 28 external inputs
- Multiplexer output's offset and gain are adjusted to increase effective ADC resolution
- Adjusted multiplexer output is buffered and routed to an MSM ADC
- Dual oscillators (off-chip crystal and on-chip RC) assure MSM sleep clock
- Crystal oscillator detector and automated switchover upon lost oscillation
- Real Time Clock for tracking time and generating associated alarms
- On-chip adjustments compensate for crystal oscillator frequency errors
- Circuits control TXCO warm-up and synchronize, deglitch, and buffer the TCXO signal
- TCXO buffer control for optimal QPH / catnap timing
- Three stage over-temperature protection (smart thermal control)



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

21

Power Management IC Features (Cont.)

4) Handset-level User Interfaces

- Four programmable current sinks for driving backlights, LEDs, and camera flash
- Driver circuit compatible with 1.2 to 3.1 V vibration motors
- Two-channel speaker driver with programmable gain, turn-on time, and muting
- Speaker inputs and outputs are configurable for stereo or mono operation
- Video (TV) amplifier drives a standard 75-Ohm port for camcorder or presentations

5) IC-level Interfaces

- Configurable SBI (3-wire or single-wire) for efficient initialization, status, and control
- Supports MSM's interrupt processing with an internal Interrupt Manager
- Many functions monitored and reported through real-time and interrupt status
- Dedicated circuits control power-on sequencing, including MSM reset
- Events continuously monitored that might trigger power-on / power-off sequences
- Supports and orchestrates soft resets
- USB-OTG transceiver for interfacing between MSM and external devices
- Two sets of RUIM level translators enable MSM interfacing with external modules

MPP Multi-Purpose Pins

- 22 pins can be configured as digital or analog I/Os, bi-directional I/Os, or current sinks

Pkg Package

- 137 CSP (7 mm x 7 mm x 1.2 mm) with a large center ground slug



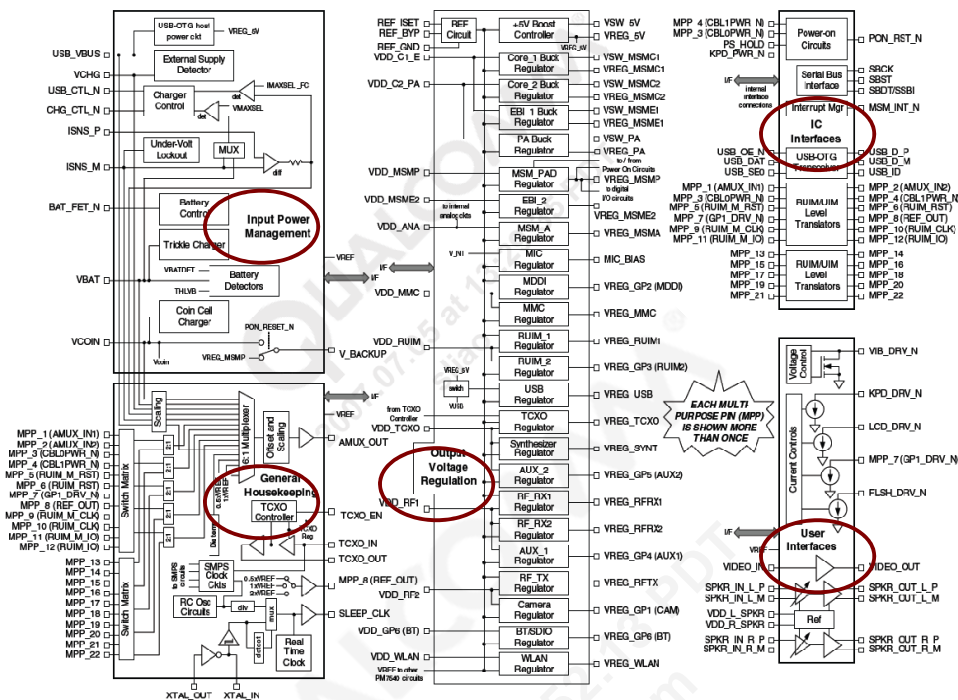
80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

22

PM7540 IC Block Diagram



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary
MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

23

Chipset Documents



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary
MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

24

MSM7627 Chipset Documentation

■ Training materials

Document	Doc #
<i>MSM7627 Chipset Training - Introduction and Chipset Overview</i>	80-VM151-21
<i>MSM7627 Chipset Training - Baseband Topics</i>	80-VM151-25
<i>MSM7627 Chipset Training - RF Transceiver IC Topics</i>	80-VM151-26

■ MSM7627 IC

Document	Doc #
<i>MSM7627 Mobile Station Modem Device Specification</i>	80-VM151-1
<i>MSM7627 Mobile Station Modem Software Interface Manual</i>	80-VM151-2
<i>MSM7627 Mobile Station Modem IC User Guide</i>	80-VM151-3
<i>MSM7627 Mobile Station Modem Revision Guide</i>	80-VM151-4



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

25

MSM7627 Chipset PMIC/RF Documentation

■ RTR6285 IC

Document	Doc #
<i>RTR6285/6280 RF Transceiver IC Device Specification</i>	80-VD861-1
<i>RTR6285/6280 RF Transceiver IC User Guide</i>	80-VD861-3
<i>RTR6285/6280 RF Transceiver IC Revision Guide</i>	80-VD861-4
<i>radioOne® Platform F/G (RFCMOS) Chipset Design Guidelines</i>	80-VD861-6

■ RTR6500 IC

Document	Doc #
<i>RTR6500 Multiband CDMA RF Transceiver IC Device Specification</i>	80-VC467-1
<i>RTR6500 Multiband CDMA RF Transceiver IC User Guide</i>	80-VC467-3
<i>RTR6500 Multiband CDMA RF Transceiver IC Revision Guide</i>	80-VC467-4
<i>RTR6500 Multiband CDMA RF Transceiver Design Guidelines</i>	80-VC467-5

■ PM7540 IC

Document	Doc #
<i>PM7540 Power Management IC Device Specification</i>	80-VD691-1
<i>PM7540 Power Management IC User Guide</i>	80-VD691-3
<i>PM7540 Power Management IC Revision Guide</i>	80-VD691-4
<i>PM7540 Power Management IC Design Guidelines</i>	80-VD691-5



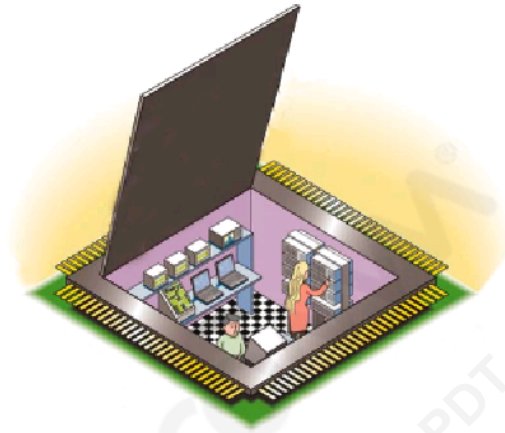
80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

26

Questions?



80-VM151-21 Rev. A
April 2009

Qualcomm Confidential and Proprietary

MAY CONTAIN U.S. AND INTERNATIONAL EXPORT CONTROLLED INFORMATION

27